0201N (.020” x .010”)

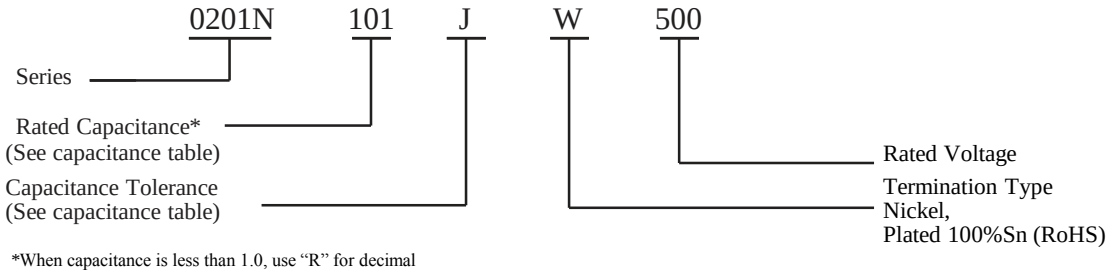
◆ 0201N Capacitance & Rated Voltage Table

Cap. pF	Code	Tol.	Rated WVDC	Cap. pF	Code	Tol.	Rated WVDC	Cap. pF	Code	Tol.	Rated WVDC
0.1	0R1	A,B, C,D	25V Code 250 Or 50V Code 500	2.2	2R2	A,B, C,D	25V Code 250 Or 50V Code 500	16	160	F,G, J,K	25V Code 250 Or 50V Code 500
0.2	0R2			2.4	2R4			18	180		
0.3	0R3			2.7	2R7			20	200		
0.4	0R4			3.0	3R0			22	220		
0.5	0R5			3.3	3R3			24	240		
0.6	0R6			3.6	3R6			27	270		
0.7	0R7			3.9	3R9			30	300		
0.8	0R8			4.3	4R3			33	330		
0.9	0R9			4.7	4R7			36	360		
1.0	1R0			5.1	5R1	B, C,D		39	390		
1.1	1R1			5.6	5R6			43	430		
1.2	1R2			6.2	6R2	B,C		47	470		
1.3	1R3			6.8	6R8			51	510		
1.4	1R4			7.5	7R5			56	560		
1.5	1R5			8.2	8R2			62	620		
1.6	1R6			9.1	9R1			68	680		
1.7	1R7			10	100	F,G, J,K		75	750		
1.8	1R8			11	110			82	820		
1.9	1R9			12	120			91	910		
2.0	2R0			13	130			100	101		
2.1	2R1			15	150						

Remark: special capacitance, tolerance and WVDC are available, consult with PASSIVE PLUS.

Note: All products are in compliance with RoHS instruction.

◆ Part Numbering

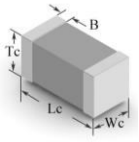


*When capacitance is less than 1.0, use "R" for decimal

Capacitance Tolerance								
Code	A	B	C	D	F	G	J	K
Tol.	±0.05pF	±0.1pF	±0.25pF	±0.5pF	±1%	±2%	±5%	±10%

◆ 0201N Chip Dimensions

unit:inch(millimeter)

Series	Term. Code	Type/Outlines	Capacitor Dimensions				Plated Material
			Length Lc	Width Wc	Thickness Tc	Overlap B	
0201N	W		.024±.001 (0.60±0.03)	.012±.001 (0.30±0.03)	.012±.001 (0.30±0.03)	.008 Max (0.20 Max)	Sn/Ni (RoHS)

◆ Design Kits

These capacitors are 100% RoHS. Kits are available in Magnetic termination that contain 10 (ten) pieces per value; number of values per kit varies, depending on case size and capacitance.

Kit	Description	Values	Tolerance
DKD0201N01	0201N .1pF - 2.0pF	0.1, 0.2, 0.3, 0.5, 0.7, 0.8, 0.9, 1.0, 1.3, 1.5, 1.7, 1.9, 2.0pF	+/-.1pF
DKD0201N02	0201N 1.0pF - 10pF	1.0, 1.3, 1.5, 1.7, 1.9, 2.0, 2.2, 2.7, 3.0, 3.9, 4.7, 5.6, 6.8, 7.5, 8.2pF,	+/.1pF
		10pF	+/-5%
DKD0201N03	0201N 10 - 100pF	10, 13, 15, 18, 20, 22, 27, 30, 39, 47, 56, 68, 75, 82, 91, 100pF	+/-5%

◆ Performance

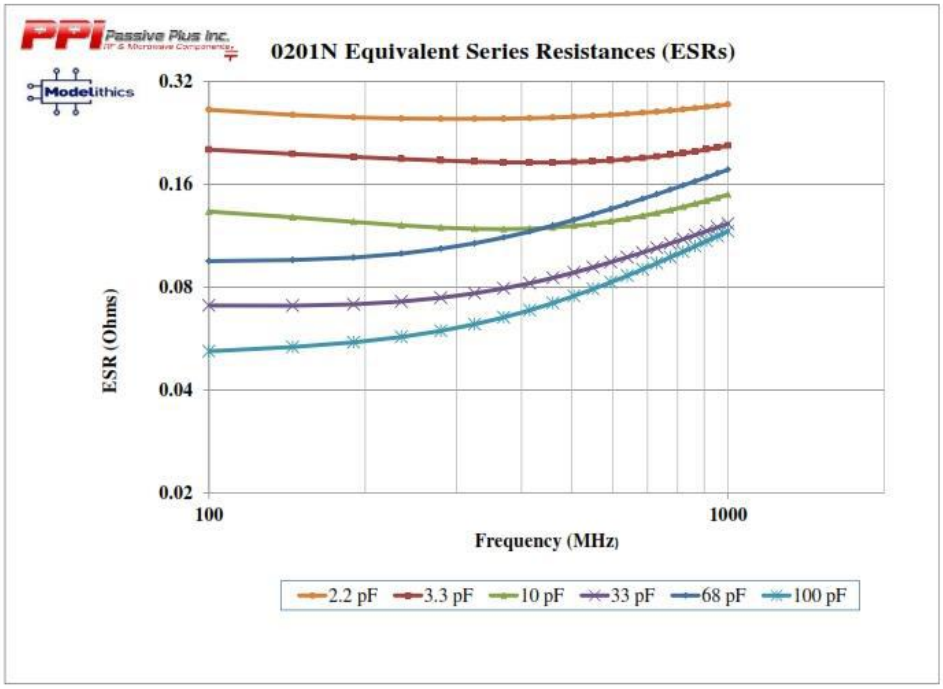
Item	Specifications
Quality Factor (Q)	2,000 min. @ 1 MHz
Insulation Resistance (IR)	10^5 Megohms min. @ +25 ℃ at rated WVDC. 10^4 Megohms min. @ +125 ℃ at rated WVDC.
Rated Voltage	25V or 50V
Dielectric Withstanding Voltage (DWV)	250% of rated Voltage for 5 seconds.
Operating Temperature Range	-55℃ to +175℃
Temperature coefficient (TC)	0±30ppm/℃
Capacitance Drift	±0.02% or ±0.02pF, whichever is greater.
Piezoelectric Effects	None

◆ Environmental Tests

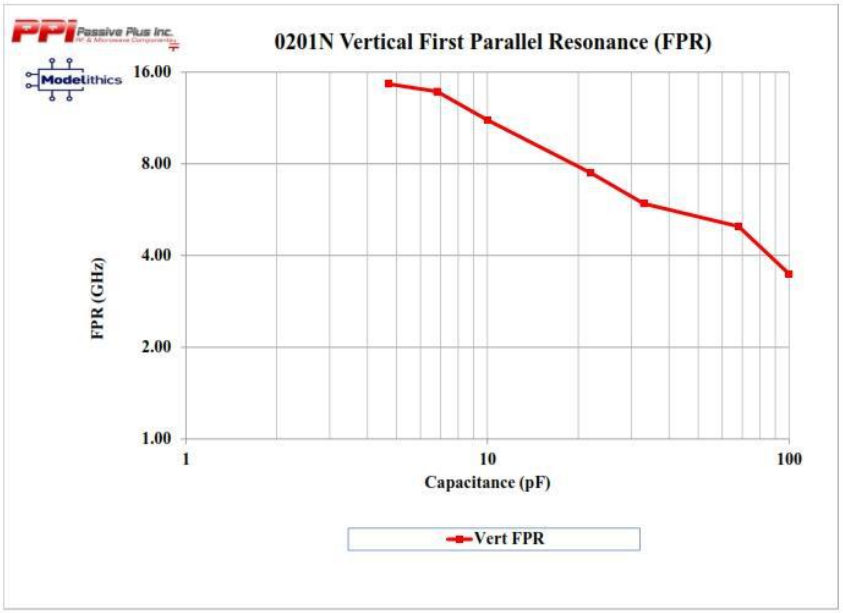
Item	Specifications	Method
Terminal Adhesion	Termination should not pull off. Ceramic should remain undamaged.	Linear pull force exerted on axial leads soldered to each terminal. 2.0lbs.
Resistance to soldering heat	No mechanical damage Capacitance change: -1.0% ~+2.0% Q>500 I.R. >10 G Ohms Breakdown voltage: 2.5 x WVDC	Preheat device to 150℃-180℃ for 60 sec. Dip in 260℃±5℃ solder for 10±1 sec. Measure after 24±2 hour cooling period.
Thermal Shock	No mechanical damage Capacitance change: ±0.5% or 0.5pF max Q>2000 I.R. >10 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 107, Condition A. At the maximum rated temperature (-55℃ and 175℃) stay 30 minutes. The time of removing shall not be more than 3 minutes. Perform the five cycles.
Humidity, Steady State	No mechanical damage Capacitance change: ±0.5% or 0.5pF max. Q>300 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 106.
Low Voltage Humidity	No mechanical damage Capacitance change: ±0.3% or 0.3pF max. Q>300 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 103, Condition A, with 1.5 Volts D.C. applied while subjected to an environment of 85℃ with 85% relative humidity for 240 hours minimum.
Life	No mechanical damage Capacitance change: ±2.0% or 0.5pF max. Q>500 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 108, for 1000 hours, at 175℃. 200% Rated voltage D.C. applied.

◆ 0201N Electrical Performance

ESR vs. Frequency



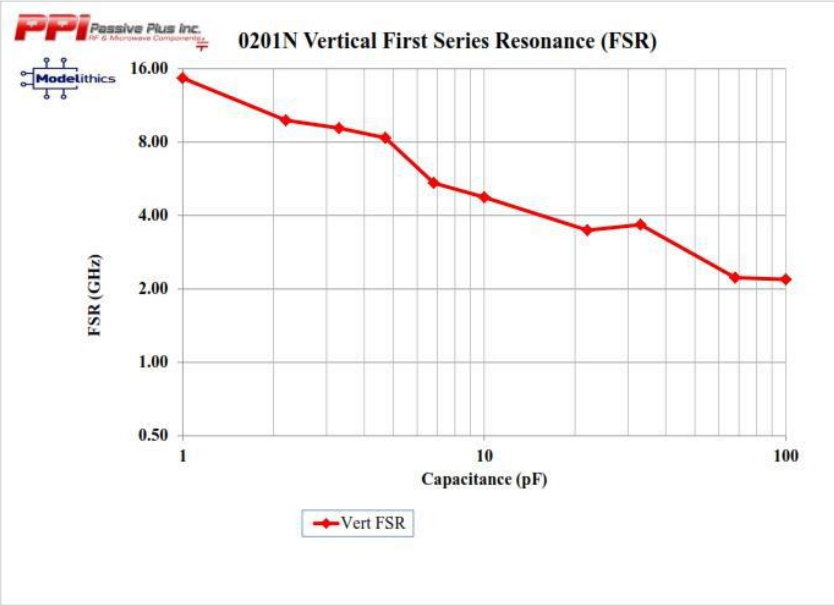
First Parallel Resonant Frequency vs. Capacitance



The First Parallel Resonance, FPR, is defined as the lowest frequency at which a suckout or notch appears in |S21|. It is generally independent of substrate thickness or dielectric constant, but does depend on capacitor orientation. A vertical orientation means the electrode planes are perpendicular to the substrate.

◆ 0201N Performance Curve

First Series Resonant Frequency vs. Capacitance



The First Series Resonance, FSR, is defined as the lowest frequency at which the imaginary part of the input impedance, Im[Zin], equals zero. Should Im[Zin] or the real part of the input impedance, Re[Zin], not be monotonic with frequency at frequencies lower than those at which Im[Zin] = 0, the FSR shall be considered as undefined. FSR is dependent on internal capacitor structure; substrate thickness and dielectric constant; capacitor orientation, as defined alongside the FPR plot; and mounting pad dimensions.

Definitions and Measurement Conditions:

The definitions on the FPR and FSR charts are for a capacitor in a series configuration, i.e., mounted across a gap in a microstrip trace with a 50-Ohm termination. The measurement conditions are: substrate -- Rogers RO3006; substrate dielectric constant = 6.15; substrate thickness (mils) = 10; gap in microstrip trace (mils) = 6.0; microstrip trace width (mils) = 14.1; **Reference planes at sample edges.**

All data has been derived from electrical models created by Modelithics, Inc., a specialty vendor contracted by PPI. The models are derived from measurements on a large number of parts disposed on several different substrates.

S-Parameters can be found on the PPI website -- http://www.passiveplus.com/index.php

◆ Recommended Land Pattern Dimensions

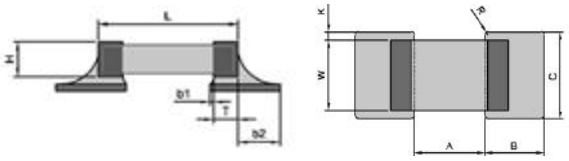
When mounting the capacitor to substrate, it's important to carefully consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

1) The greater the amount of solder, the greater the stress to the elements. This may cause the substrate to break or crack.

2) In the situation where two or more devices are mounted onto a common land, be sure to separate the device into exclusive pads by using soldering resist.

◆ Horizontal Mounting

Orientation	EIA	A	B	C
Horizontal	0201	0.28	0.28	0.37



◆ Tape & Reel Specifications

Orientation	EIA	A0	B0	K0	W	P0	P1	T	F	QTY Min	QTY/ REEL	Tape Material
Horizontal	0201N	0.406	0.749	0.422	8.00	4.00	2.00	0.42	3.50	500	500	Paper

◆ Horizontal Orientation